

CMP defects: Influence of CMP slurry, handling and delivery

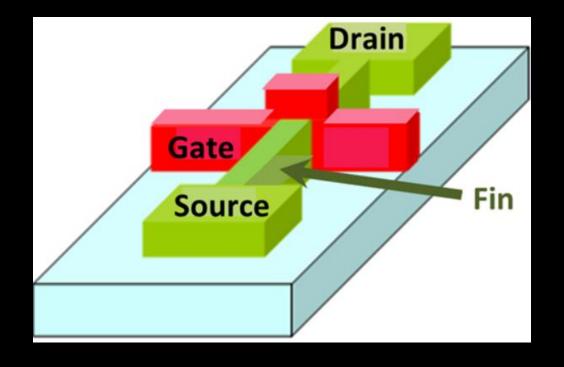
2020 CMPUG: Advancements in CMP Applications and Research

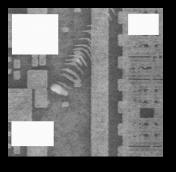
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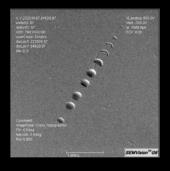


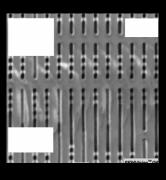
Introduction



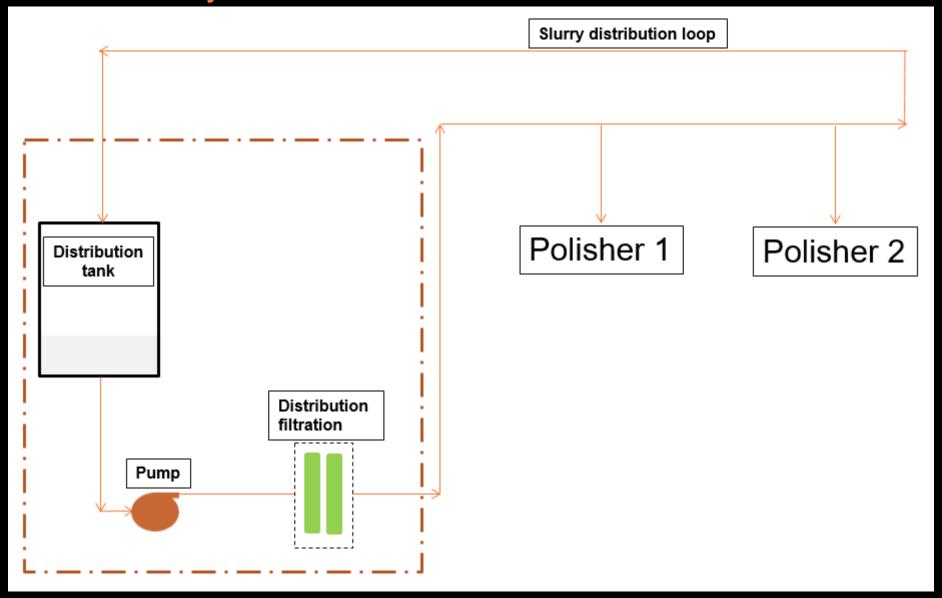






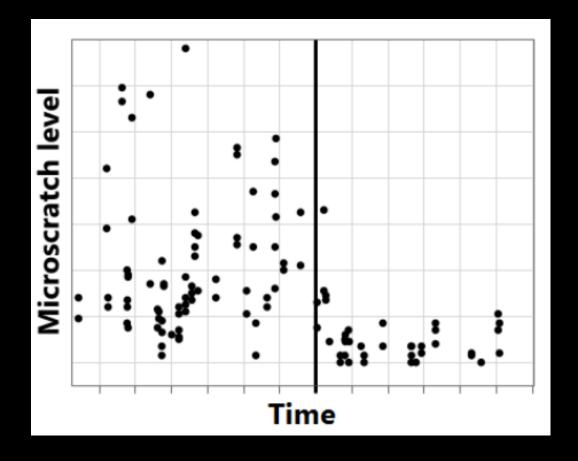


Slurry Distribution System



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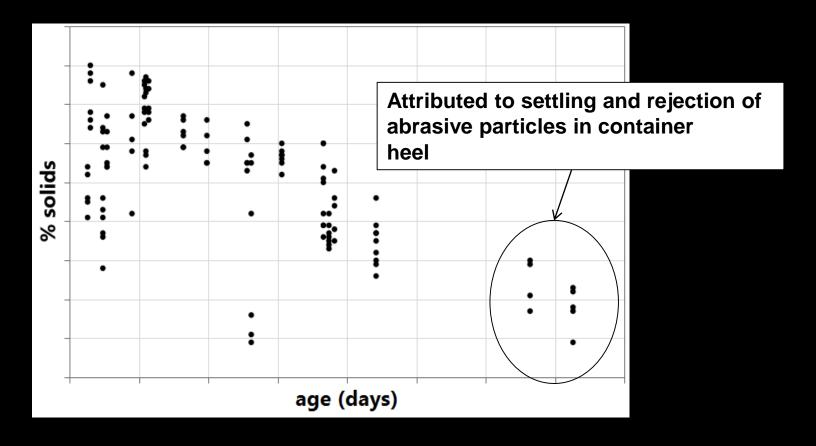
Loop Preparation



Reduction in Microscratches because of loop preparation

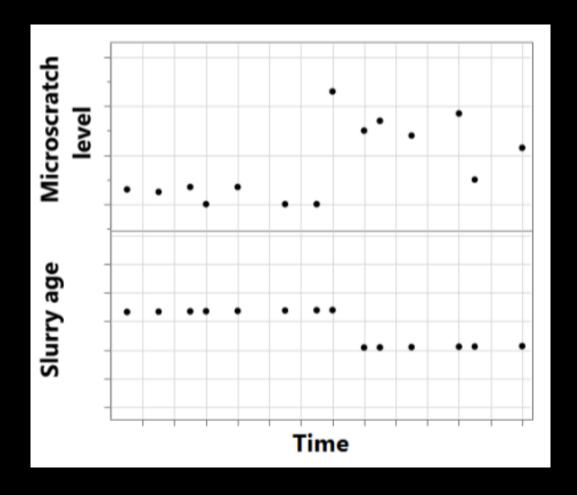
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Slurry Age



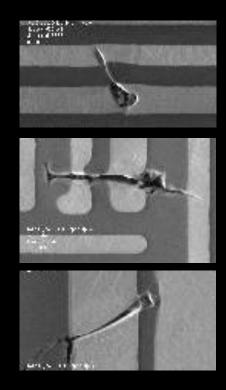
% solids in distribution loop Vs slurry age

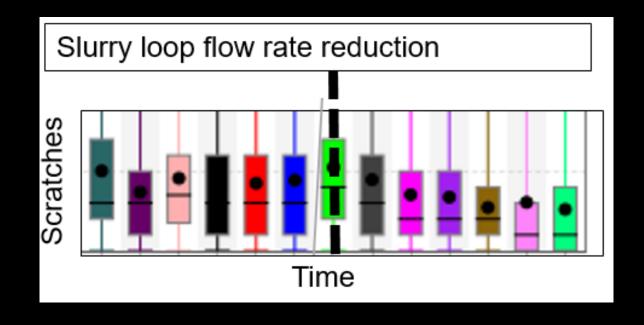
Slurry Age



Correlation between slurry age and Microscratch level

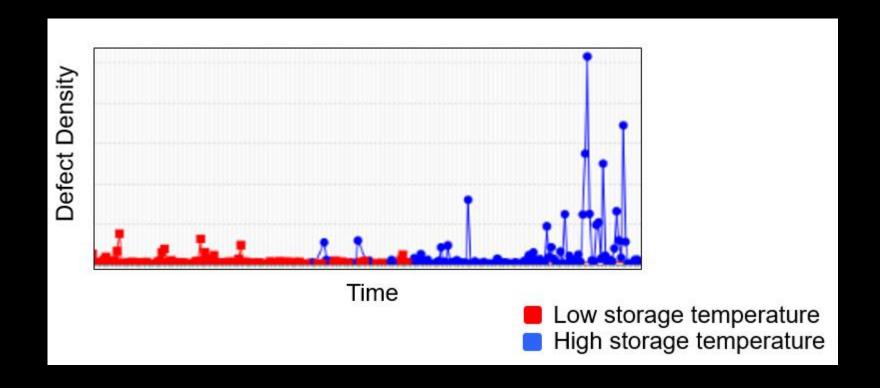
Loop Flow Rate





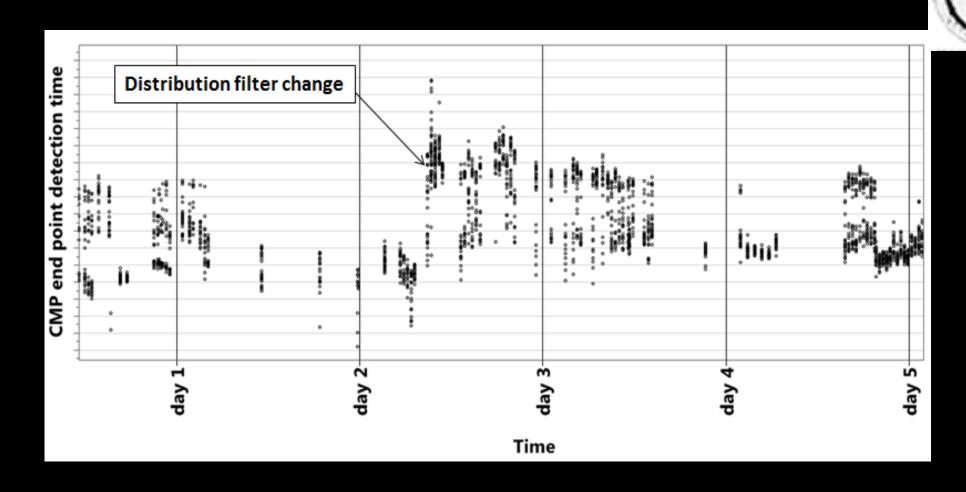
Improvement in Scratches with slurry loop flow rate reduction

Slurry Storage Temperature



Modulation in defect density with raw slurry storage temperature

Filtration



FEOL oxide CMP end point detection time trend

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Conclusion

 As device geometries shrink, CMP slurry, handling & delivery play an important role in modulating defects

Slurry parameters present an important opportunity in defect reduction

Acknowledgements

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Thank you

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